Wireless CPU Q24 Series Differences with the WISMO Quik Q24xx series

Revision: 002 Date: September 2006



Operating Systems Plug-Ins Integrated Development Environments Wireless CPUs Services



Differences with the WISMO Quik Q24xx series

Reference: WM_PRJ_024NG_PTS_004 Revision: 002 Date: September 2006

The Wireless CPU Q24 Series is pin to pin compared to the previous WISMO QUIK Q24xx sub-series, and offers improvements such as:

- Wider RF connectivity
- Quad band
- Improved RF performances
- Reduced power consumption
- SIM 3V/1V8 supported
- Optional integrated SIM CARD connector
- Voltage regulator output available (up to 100mA)
- Back-up battery regulator available



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Page: 1 / 24



Cautions

This platform contains a modular transmitter. This device is used for wireless applications. Note that all electronics parts and elements are ESD sensitive.

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Page: 2 / 24



Web Site Support

General information about Wavecom and its range of products: <u>www.wavecom.com</u> Specific support is available for the Q24 Classic, Plus, Extended and Auto Wireless CPU: <u>www.wavecom.com/Q24Classic</u>,

www.wavecom.com/Q24Plus,

www.wavecom.com/Q24Extended,

www.wavecom.com/Q24Auto

Carrier/Operator approvals: www.wavecom.com/approvals

Open AT® Introduction: www.wavecom.com/OpenAT

Developer support for software and hardware: www.wavecom.com/forum

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This document summarizes the difference between the Wireless CPU Q24 series (available in four GSM/GPRS Class 10 quad-band versions) and the WISMO Quik Q24xx sub-series.

The Wireless CPU Q24 versions are:

- **Q24 Classic: EGSM 900/1800/850/1900** MHz version with **32** Mb of Flash memory and 16 Mb of PSRAM **(32/16)**, T° range **[-20°C / +55°C]**.
- **Q24 Plus: EGSM/GPRS 900/1800/850/1900** MHz version with **32** Mb of Flash memory and 16 Mb of PSRAM **(32/16)**, T° range **[-20°C / +55°C]**.
- **Q24 Extended: EGSM/GPRS 900/1800/850/1900** MHz version with **32** Mb of Flash memory and 4 Mb of SRAM **(32/4)**, Extended T° range.
- **Q24 Automotive: EGSM/GPRS 900/1800/850/1900** MHz version with **32** Mb of Flash memory and 4 Mb of SRAM **(32/4)**, Extended T° range.

The WISMO Quik versions are:

- Q2400A: EGSM 900/1800 MHz version with 16 Mbits of Flash memory and 2 Mbits of SRAM (16/2).
- **Q2406A**: EGSM/GPRS **900/1800** MHz version with **16** Mbits of Flash memory and 2 Mbits of SRAM (16/2).
- **Q2406B: EGSM/GPRS 900/1800** MHz version with **32** Mbits of Flash memory and **4** Mbits of SRAM (32/4).
- **Q2426A: GSM/GPRS 850/1900** MHz version with **16** Mbits of Flash memory and **2** Mbits of SRAM (16/2).
- **Q2426B: GSM/GPRS 850/1900** MHz version with **32** Mbits of Flash memory and **4** Mbits of SRAM (32/4).

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Document History

Revision	Date	List of revisions	
001	May 2006	Creation (Preliminary version)	
002	August 2006	Update GPC difference list Update mechanical drawings with new SIM holder	

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Contents

	Reter	ences	8
1.1	Refe	erence Documents	8
1.	.1.1		8
1.	.1.2	General Reference Documents	8
1.2	Abb	previations	9
2	Gene	ral Description	12
2.1	Gen	neral Information	
2.2	Fun	ctional Differences	
2.	.2.1	RF Band	
2.	.2.2	T° Range	
2.	.2.3	RF Connection, Connector Type and Position	14
2.3	Gen	neral Purpose Connector Pin out Differences	
2.4	Pov	ver Supply Differences	
2.5	Pov	ver Consumption Differences	
2.6	Med	chanical Differences	
2.	.6.1	RF Interfaces	
2.	.6.2	SIM Interfaces	22

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Table of figures

Figure 1: Product correspondence	. 12
Figure 2: The new antenna pad position	. 14
Figure 3: MMS connector position	. 14
Figure 4: Mechanical drawing of the Wireless CPU series	. 22
Figure 5: Mechanical drawing of the Wireless CPU series +SIM CARD holder	. 22

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References

1 References

1.1 Reference Documents

For more details, several reference documents may be consulted. The Wavecom reference documents are provided in the Wavecom documents package contrary to the general reference documents, which are not Wavecom owned.

1.1.1 Wavecom Reference Documents

- [1] Automotive Environmental Control Plan for Wireless CPU Q24 series WM_PRJ_Q24NG_DCP_001
- [2] Environmental Control Plan for Wireless CPU Q24 series WM_PRJ_Q24NG_DCP_002
- [3] Wireless CPU Q24 series Customer Design Guidelines WM_PRJ_Q24NG_PTS_002
- [4] Wireless CPU Q24 series Process Customer Guidelines WM_PRJ_Q24NG_PTS_003
- [5] AT Commands Interface Guide for OS 6.57 WM_ASW_OAT_UGD_0044
- [6] AT Commands Interface Guide (Bluetooth) WM_ASW_BLU_UGD_001
- [7] ADL User Guide for Open ATA® V3.12 WM_ASW_OAT_UGD_006
- [8] Wireless CPU Q24NG Product Technical Specification WM_PRJ_Q24NG_PTS_001

1.1.2 General Reference Documents

- [9] "I²C Bus Specification", Version 2.0, Philips Semiconductor 1998
- [10] ISO 7816-3 Standard

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References

1.2 Abbreviations

Abbreviation	Description
3GPP	Third Generation Partnership Project
ADC	Analog to Digital Converter
A/D	Analog to Digital conversion
AT	ATtention (prefix for modem commands)
AUX	AUXiliary
CBS	Cell Broadcast Service
CLK	CLocK
CMOS	Complementary Metal Oxide Semiconductor
CODEC	COder DECoder
CPU	Central Processing Unit
CTS	Clear To Send
dB	Decibel
DC	Direct Current
DCD	Data Carrier Detect
DCS	Digital Cellular System
DCXO	Digitally controlled crystal oscillator
DR	Dynamic Range
DSR	Data Set Ready
DTR	Data Terminal Ready
EDGE	Enhanced Data rates for GSM Evolution
EGSM	Extended GSM
EN	ENable
ESD	ElectroStatic Discharges
ETSI	European Telecommunications Standards Institute
FEM	Front End Module
FR	Full Rate
GND	GrouND
GPI	General Purpose Input
GPC	General Purpose Connector
GPIO	General Purpose Input Output
GPO	General Purpose Output
GPRS	General Packet Radio Service

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Page: 9 / 24



References

Abbreviation	Description
GSM	Global System for Mobile communications
IF	Intermediate Frequency
INTR	INTeRrupt
I/O	Input / O utput
LCD	Liquid Crystal Display
LED	Light Emitting Diode
LNA	Low Noise Amplifier
LSB	Less Significant Bit
MAX	MAXimum
MIC	MICrophone
MIN	MINimum
MMS	Multimedia Message Service
MS	Mobile Station
NOM	NOMinal
NTC	Negative Temperature Coefficient
PA	Power Amplifier
PBB	PolyBrominated Biphenyl
PBDE	PolyBrominated Diphenyl Ethers
PCB	Printed Circuit Board
PCL	Power Control Level
PCS	Personal Communications Services
PLL	Phase Lock Loop
RAM	Random Access Memory
RF	Radio Frequency
RI	Ring Indicator
RoHS	Restriction of Hazardous Substances
RST	ReSeT
RTC	Real Time Clock
RTS	Request To Send
RX	Receive
SCL	Serial CLock
SDA	Serial DAta
SIM	Subscriber Identification Module
SMS	Short Message Service

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Page: 10 / 24



Wireless CPU Q24 series References

Abbreviation	Description
SPI	Serial Peripheral Interface
SPK	SPeaKer
SRAM	Static RAM
TDMA	Time Division Multiple Access
TU	Typical Urban fading profile
TUHigh	Typical Urban, High speed fading profile
TDMA	Time Division Multiple Access
ТХ	Transmit
TYP	TYPical
UART	Universal Asynchronous Receiver-Transmitter
VLSI	Very Large Scale Integration
VSWR	Voltage Standing Wave Ratio

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2 General Description

2.1 General Information

The Wireless CPU Q24 series is offered in four different versions. The denomination used for WISMO Quik Q24xx series is no more applicable. The table below defines for each WISMO QUIK Q24XX series product the Wireless CPU version.

Q24 Classic	Q24 Plus	Q24 Extended	Q24 Automotive
Quad-band GSM 1 to 6 MIPS -20/+55°C Optional SIM Holder	Quad-band GSM / GPRS 9 to 13 MIPS -20/+55°C Numerous plug-ins Optional SIM Holder	Quad-band GSM / GPRS 9 to 13 MIPS -40/+85°C Numerous plug-ins Optional SIM Holder	Quad-band GSM / GPRS 9 to 13 MIPS -40/+85°C MMS connector Numerous plug-ins Automotive qualified Traceability
Replaces Q2400A	Replaces Q2406B, Q2426B		Replaces Q24-C

Figure 1: Product correspondence

The differences between the Wireless CPU Q24 series and WISMO Quik Q24xx subseries are detailed below.

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General Description

2.2 Functional Differences

2.2.1 RF Band

As per definition in the previous dual-band WISMO Quik Q24xx sub-series, the Wireless CPU Q24 series products are quad-band as described in the table below:

Product reference	RF band
Q2400-A	EGSM 900/1800 MHz
Q24 Classic	EGSM 850/900/1800/1900 MHz
Q2406-B	EGSM/GPRS CL 10 900/1800 MHz
Q2426-B	EGSM/GPRS CL 10 850/1900 MHz
Q24 Plus	EGSM/GPRS CL 10 850/900/1800/1900 MHz
Q2406-C	EGSM/GPRS CL 10 900/1800 MHz
Q24 Automotive	EGSM/GPRS CL 10 850/900/1800/1900 MHz

RF capabilities

2.2.2 T° Range

The Q24 Extended is an additional product offered with the Wireless CPU range, compared to the WISMO Quik range. The Q24 Extended is compliant with an Extended T^o range as described in the table below:

T° range capabilities

Product reference	T°range
Q2400-A	-20°C + 55°C Class A
Q24 Classic	-20°C + 55°C Class A
Q2406-B	-20°C + 55°C Class A
Q2426-B	-20°C + 55°C Class A
Q24 Plus	-20°C + 55°C Class A
	-20°C + 55°C Class A
Q24 Extended	-30°C + 75°C Class B
	-40°C + 85°C Class C
	-20°C + 55°C Class A
Q2406-C	-30°C + 75°C Class B
	-40°C +85°C Class C
	-20°C + 55°C Class A
Q24 Automotive	-30°C + 75°C Class B
	-40°C +85°C Class C

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General Description

2.2.3 RF Connection, Connector Type and Position

All the previous RF connections offered by the WISMO Quik Q24xx sub-series are also supported by the Wireless CPU Q24 series.

One of the key improvements of the Wireless CPU Q24 series range is the RF connection offered to customers.

In addition to the antenna pad (dedicated to coaxial cable), it is also possible to use UFL connector, MMS connector or an IMP connector for the antenna connection.

The connectors offered for each version of the Wireless CPU range compared to the WISMO Quik Q24xx sub-series are described in the table below:

Product reference	UFL on bottom side	UFL or MMS on top side	Antenna pad on top side	IMP on bottom side
Q2400 A			Х	
Q24 Classic	Х		Х	Х
Q2406-B			Х	
Q2426-B			Х	
Q24 Plus	Х		Х	Х
Q24 Extended	Х		Х	Х
Q2406-C		Х	Х	
Q24 Automotive		Х	Х	Х



The antenna pad and MMS connector positions are slightly different on the Wireless CPU Q24 series; the coaxial cable compatibility used on a WISMO Quik Q24xx subseries must be carefully checked. This is also the case for the MMS connector position

This new implementation is more flexible, in particular, the way in connecting the RF cable to the Wireless CPU Q24 series, offers **a wider angular position**.

The figures below describe in detail the new antenna pad position and the new MMS connector position (see next pages)

Figure 2: The new antenna pad position

Figure 3: MMS connector position

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Page: 14 / 24



DATE	20/03/2006			
VERSION	V1.0	waveco		
ENG	HTO/ FPA MLR	confidential (C)		
TITLE	Position	Pointe RF	SCALE 024mm	
PROJECT	Q24	NG 4RF	FORMAT	
N≗ D'IDENTIFIANT WM0600101-001-10				
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	26/03/2006	waveco		
ENG	HTO/ FPA MLR	confidential (C)		
TITLE	DIFF-P(OSITION MMS	SCALE D 2 4 mm	
PROJECT	Q2	24NG	FORMAT	
$\bigvee_{\mathfrak{S}} =$	D'IDENTIFIANT	WM0600101-00)1-10	
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Wireless CPU Q24 series General Description

	l v		224xx	Wireless CPU Q24 series			
Pin #	Signal Name	Function	Value Signal Name		Function	Value	
55 57 58 59 60	VBATT	Battery Input	3.3V to 4.5V	VBATT	Battery Input	3.2V to 4.5V	
3	SIM- CLK CLK Clock for SIM interface		2.8V	SIM-CLK	Clock for SIM interface	2.9V or 1.8V	
5	SIM- RST	Reset for SIM interface	2.8V	SIM-RST	Reset for SIM interface	2.9V or 1.8V	
6	ON/OFF	Power ON/OFF control	Low logic=0 to 0.6V High logic =2.4V to VBATT +0.5V	ON/OFF	Power ON/OFF control	Low logic=0 to 0.6V High logic= 2.4V to 5V	
7	SIM- DATA	I/O SIM interface	2.8V	SIM-DATA	I/O SIM interface	2.9V or 1.8V	
9	SIM- VCC	SIM card supply	2.8V	SIM-VCC	SIM card supply	2.9V or 1.8V	
40	VCC	2.8V digital supply output	2.8V /10mA	VCC-2.8V	2.8V digital supply output	2.8V /100mA	
49	BUZZER	Buzzer output	80mA peak /Open BUZZER Buzzer output collector		100mA peak /Open drain		

2.3 General Purpose Connector Pin out Differences

2.4 Power Supply Differences

A power supply designed for WISMO Quik Q24xx sub-series is fully usable for any product in the Wireless CPU Q24 series.

2.5 Power Consumption Differences

The table below aims to summarize the power consumption differences between the WISMO Quik Q24xx family and the Wireless CPU Q24 series, using the same Operating System (OS 6.57)

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General Description

	Parameters		INOM a	verage	Difference	Unit
Operating mode			New Q24	Q24xx	New Q24/Q24xx	
OFF Mode			16.5	7	9.5	μA
Alarm Mode			18.5	9	9.5	μA
Foot Idlo Modo	Paging 9		10.5	9.5	1	mA
Fast fulle Mode	Pagi	ng 2	13	12	1	mA
Slow Idle Mode 1	Paging 9		2.8	2.5	0.3	mA
	Paging 2		5.5	5.5	0	mA
Fast Standby	VBATT = 3.6V		9.5	8.5	1	mΑ
Slow Standby	VBATT = 3.6V		1.5	1.5	0	mA
	GSM850	PCL5	217	300	-83	mA
Connected Mode	EGSM900	PCL19	90	100	-10	mA

2.6 Mechanical Differences

2.6.1 RF Interfaces

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Except for the position of Antenna pad and MMS connector (refer to section 2.2.3), the Wireless CPU Q24 series is compatible with the WISMO Quik Q24xx sub-series.

• The position of 60-pin GPC is exactly the same.

The shielding frame and cover has been updated for the Wireless CPU Q24 series, but is compatible for any application designed with a WISMO Quik Q24xx sub-series.

• The four legs positions remain the same.

RF connectors IMP/UFL and MMS were not offered with WISMO Quik Q24xx sub series.

Detailed specifications of these connectors may be found below:

• The supplier for the IMP connector is Radiall (<u>http://www.radiall.com</u>) with the following reference:

R107 064 900 or R107 064 902

• The supplier for the MMS connector is Radiall (<u>http://www.radiall.com</u>); detailed datasheet of this connector and associated cable is given below.



GENERAL



50 Ω	DC - 6 GHz
75 Ω	DC - 1 GHz

GENERAL

- Low profile coaxial connectors
- Surface-mount receptacle (SMT)
- Fully compatible with automated pick and place machines
- Snap-on mating
- High RF performance :
 VSWR : 1.05 at 1 GHz / 1.15 at 2.5 GHz
 RF leakage : -40 dB at 2 GHz
- Competitive pricing

APPLICATIONS

- Base stations and hand-sets for :
 cellular telephones
 cordless telephones
- Satellite reception terminals (GPS, . . .)
- Instrumentation
- Wireless datacom networks
- Automated payment systems
- Videocommunications
- Other general electronics





CHARACTERISTICS

	TEST STANDARD	RESULTS		
ELECTRICAL CHARACTERISTICS				
Impedance		50 Ω	75 Ω	
Frequency range		DC-6 GHz	DC-1 GHz	
V.S.W.R. (mated pair)	IEC 1169-1	1.05 at 1 GHz 1.15 at 2.5 GHz 1.35 at 6 GHz		
Insertion loss	IEC 1169-1	0.2 dB at 2 GHz		
RF leakage (mated pair)	MIL STD 1344 method 3008	-50 dB at 500 MHz -45 dB at 1 GHz -40 dB at 2 GHz		
Outer contact resistance	NF-C 93050 (I = 40 mA peak)	5m Ω max		
Center contact resistance	NF-C 93050 (I = 40 mA peak)	15m Ω max		
Insulation resistance	IEC 1169-1	500 M Ω min (under 250 V	RMS)	
Working voltage		50 V RMS		
Testing voltage (V RMS)	IEC 1169-1	Ø 1 mm : 250 ; Ø 2 mm :	500	
Maximum admissible power		40 W at 1 GHz / 20°C / V.S.W.R. = 1		
MECHANICAL CHARACTERISTICS				
Durability	IEC 1169-1	50 matings		
Force to engage	IEC 1169-1	7 N avg		
Force to disengage	IEC 1169-1	5.5 N avg		
Shocks (drop test)	IEC 68-2-27	50 g/11 ms ; 3 shocks/axis	/way	
Random vibrations	Général Motors spec.	Sine waves 5 to 1000 Hz 3 to 30g - 1 H/axis		
Bumps (mechanical shocks)	IEC 68-2-29	25 g/6 ms 1000 bumps/axi	s/way	
Cable retention force	IEC 1169-1	Ø 1 mm : 20 N ; Ø 2 mm :	35 N	
Solderability	IEC 68-2-54	Passed		
ENVIRONMENTAL CHARACTERISTICS				
Temperature range	r	-40°C / +90°C		
Climatic cycles	GAM I 13	48 H at 70° C - 24 H at 40	° C/93% -36 H at -25°C	
MATERIALS				
Bodies plugs / in series adapters	Die cast zinc / brass			
Bodies receptacles	Phosphor bronze			
Center contact male female	Brass Beryllium copper			
Insulator	PTFE			
PLATING				
Bodies plugs, in series adapters	Nickel			
Bodies receptacles	Gold			
Center contact male	Nickel			

POWER RATING

female

Example : P = 23 W at F = 1.8 GHz, T = 40 °C, V.S.W.R. = 1.1 For any further information about the power handled, please see our power application guide (*D1 033 DE*).

Gold



All dimensions are given in mm.



STANDARD CABLE ASSEMBLIES

MMS PIGTAILS





cable group	part number	composition	
1 /50/ S	R285 001 001	R209 351 020 + C291 050 066	
2 /50/ S	R285 001 021	R209 353 000 + C291 145 060	
2 /50/ D	R285 001 031	R209 355 000+ C291 146 087	
2 /75/ S	R285 001 041	R209 353 000 + C291 305 000	

MMS CABLE ASSEMBLIES



2 /50/ S



R209 353 000 + C291 145 060 + R141 323 000

cable group	part number	fig.	composition
1 /50/ S	R285 004 001	1	R209 351 020 + C291 050 066 + R209 351 020
1 /50/ S	R285 005 001	2	R209 351 020 + C291 050 066 + R209 351 020
2 /50/ S	R285 004 221	1	R209 353 000 + C291 145 060 + R209 353 000
2 /50/ S	R285 005 221	2	R209 353 000 + C291 145 060 + R209 353 000
2 /50/ S	R285 003 221	3	R209 080 000 + C291 145 060 + R209 353 000

BETWEEN SERIES CABLE ASSEMBLIES

R285 031 221



2

MMS/BNC



General Description

A wide variety of cables fitted with UF-L connectors are proposed by HIROSE:

- UF-L pigtails,
- UF-L cable assemblies,
- Between series cable assemblies.

2.6.2 SIM Interfaces

The Wireless CPU Q24 Classic and Plus are proposed with an additional SIM interface:

A SIM CARD holder may be equipped on the top of the Wireless CPU.

If a SIM CARD holder is used; the thickness of this connector must be taken into account.

The figures shown in the next pages are detailed mechanical drawing of the Wireless CPU Q24 series, with and without SIM CARD holder.

Figure 4: Mechanical drawing of the Wireless CPU series

Figure 5: Mechanical drawing of the Wireless CPU series +SIM CARD holder



Customers are advised to verify that the SIM Card environmental specification used is compliant with the Wireless CPU Q24NG environmental specifications. Please refer to [8] Wireless CPU Q24NG Product Technical Specification WM_PRJ_Q24NG_PTS_001. Any application must be qualified by the customer with the SIM Card in storage, transportation, and operation.

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WAVECOM S.A. - 3 esplanade du Foncet - 92442 Issy-les-Moulineaux Cedex - France - Tel: +33(0)1 46 29 08 00 - Fax: +33(0)1 46 29 08 08 Wavecom, Inc. - 4810 Eastgate Mall - Second Floor - San Diego, CA 92121 - USA - Tel: +1 858 362 0101 - Fax: +1 858 558 5485 WAVECOM Asia Pacific Ltd. - Unit 201-207, 2nd Floor, Bio-Informatics Centre – No.2 Science Park West Avenue - Hong Kong Science Park, Shatin - New Territories, Hong Kong

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